

Use Of Moisture Sensitive Devices Label For ZFx86

Label

All shipments from ZF Micro Devices are labelled with a fluorescent green packaging label that clearly gives baking instructions, shelf life, body temperature, and other pertinent information. All production personnel working with ZFx86 devices should read and become familiar with the instructions and information on that label.

Label Appearance



CAUTION

This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL

3

1. Shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
2. Peak package body temperature: 125°C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 72 hours at factory conditions of $\leq 30^{\circ}\text{C} / 60\% \text{ RH}$, or
 - b. Stored at $< 10\% \text{ RH}$
4. Devices require bake, before mounting, if:
 - a. Humidity Indicator Card is $> 10\%$ when read at $23 \pm 5^{\circ}\text{C}$, or
 - b. 3a or 3b is not met.
5. If baking is required, devices must be baked for 8 hours at $125 \pm 5^{\circ}\text{C}$

Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-020 for bake procedure.

Bag seal date: _____

(if blank, see bar code label)

Note: if these devices must be demounted from the PC board, the PC board must first be baked to dry the packages to prevent cracking during removal.

1. Bake 8 hours at 125°C , or as per IPC/JEDEC J-STD-020.
2. Demount within 16 hours after baking.

2740-0018-00A



Text Of Label

The text on the label is as follows:

CAUTION

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2. Peak package body temperature: 125°C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 72 hours at factory conditions of equal to or less than 30°C / 60% RH, or
 - b. Stored at $< 10\%$ RH
4. Devices require bake, before mounting, if:
 - a. Humidity Indicator Card is $>10\%$ when read at $23\pm 5^{\circ}\text{C}$, or
 - b. 3a or 3b is not met.
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Label P/N: 2740-0018-00A, Title: LABEL, MOISTURE SENSITIVE PARTS, ZFx86 (Formerly MACHZ)